

Application No. 09/802,792

Please substitute the following amended paragraph for the pending paragraph beginning on page 7, line 28:

B2
Figure 4 is a plan view showing the configuration of various types of filtering layers 74 over a chip 10 and an adjacent chip 10' within a wafer. In this particular embodiment, there is provided a relatively short "scribe area" 75 of otherwise unused wafer area between chips 10 and 10', and successive blade cuts are used to cut through the respective grooves 70 and 70', as described, for example, in U.S. Patent 5,219,796. As shown, in this view there are provided three distinct filtering layers, indicated as 74A, 74B, and 74C, which respectively cover rows of photosites 14 described above as 16A, 16B, and 16C. Typically, the three types of filters 74 will each transmit only one primary color, red, green, or blue, so that the chip 10 itself can output image data reflective of the entire visible spectrum, as is familiar in the art. Significantly, as shown in Figure 4, the respective areas covered by filters 74A, 74B, and 74C each extend over one linear array, i.e., rows 16A, 16B, and 16C of photosites 14; and the same filter area such as 74A for one chip 10 extends across the groove 70, scribe area 75, another groove 70', and over the equivalent row such as 16A for the adjacent chip 10'. Indeed, if there are a number of chips 10 in a row along one dimension in a wafer, each filtered area should extend across the suitable row 16 of photosites for as many chips 10 as is geometrically possible. Once again, where a filter 74 extends over a groove 70, the filter 74 is disposed over and supported by a clear layer 72 (as shown in Figure 3) which presents a substantially planar surface over the groove 70.

IN THE CLAIMS:

Please substitute amended claims 20 and 31 for pending claims 20 and 31 as follows: